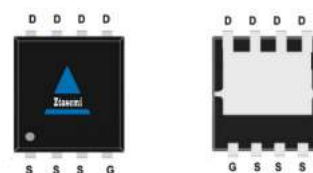


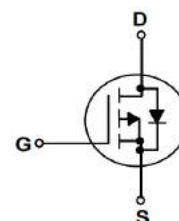
Features

- P-Channel
- Very low on-resistance $R_{DS(on)}$
- Low C_{rss}
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 100% EAS Tested

V_{DS}	-30	V
$R_{DS(on),TYP@ V_{GS}=-10V}$	9	m Ω
$R_{DS(on),TYP@ V_{GS}=-4.5V}$	14	m Ω
I_D	-50	A

DNF3x3


Part ID	Package Type	Marking	Packing
ZT090P03Q	DNF3x3	ZT090P03Q	5000pcs/reel



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings ($T_C=25^\circ\text{C}$ Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	± 25	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-30	V	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_C = 25^\circ\text{C}$ -200	A	
Mounted on Large Heat Sink				
I_D	Drain Current-Continuous	$T_C = 25^\circ\text{C}$	-50	A
		$T_C = 100^\circ\text{C}$	-33	A
P_D	Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	20	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	6.25	$^\circ\text{C/W}$	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed (Note 2)	225	mJ	

Electrical Characteristics (T_j=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_j=25°C (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-30	--	--	V
IDSS	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V	--	--	-1	μA
IGSS	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.0	-1.5	-2.0	V
RDS(on)	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-12A	--	9	10.5	mΩ
RDS(on)	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-7A	--	14	17	mΩ
Dynamic Electrical Characteristics @ T_j = 25°C (unless otherwise stated)						
Ciss	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	--	1770	--	pF
Coss	Output Capacitance		--	231	--	pF
Crss	Reverse Transfer Capacitance		--	216	--	pF
Rg	Gate Resistance f=1MHz	f=1MHz	--	2.5	--	Ω
Qg	Total Gate Charge	V _{DS} =-15V, I _D =-25A, V _{GS} =-10V	--	32	--	nC
Qgs	Gate-Source Charge		--	6	--	nC
Qgd	Gate-Drain Charge		--	10	--	nC
Switching Characteristics						
Td(on)	Turn-on Delay Time	V _{DS} =-15V, I _D =-25A, R _G =3Ω, V _{GS} =-10V	--	13	--	ns
Tr	Turn-on Rise Time		--	8.5	--	ns
Td(off)	Turn-Off Delay Time		--	26	--	ns
Tf	Turn-Off Fall Time		--	12	--	ns
Source- Drain Diode Characteristics @ T_j = 25°C (unless otherwise stated)						
ISD	Source-Drain Current (Body Diode)		--	--	-50	A
VSD	Forward on voltage (Note 3)	I _S = -10A, V _{GS} =0V	--	--	-1.2	V
Trr	Reverse Recovery Time	T _j =25°C, I _F = -25A, V _{GS} =0V	--	32	--	ns
Qrr	Reverse Recovery Charge	di/dt=100A/μs	--	21	--	nC

Notes :

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2.E_{AS} condition: T_j=25°C, V_{DD}=-20V, V_G=-10V, R_G=25Ω, L=0.5mH.
- 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

P- Channel Typical Characteristics

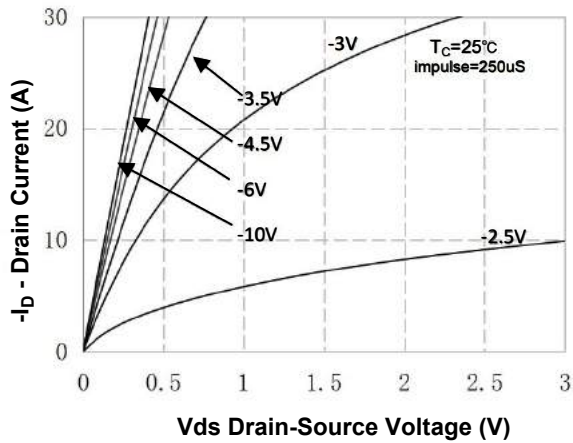


Figure 1. On-Region Characteristics

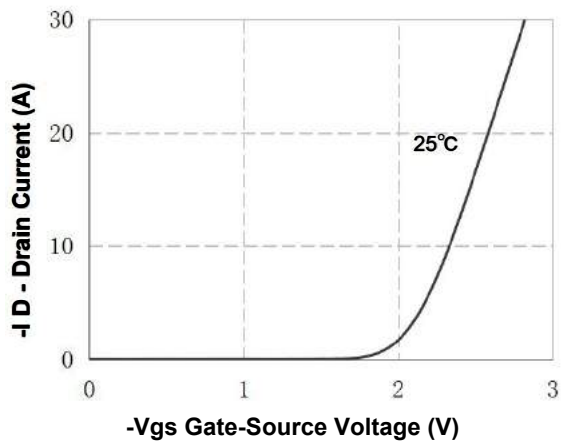


Figure 4. Transfer Characteristics

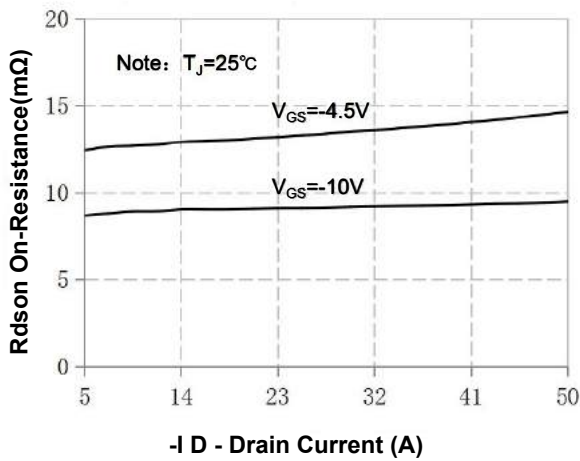


Figure 2. On-Resistance Variation vs Drain Current and Gate Voltage

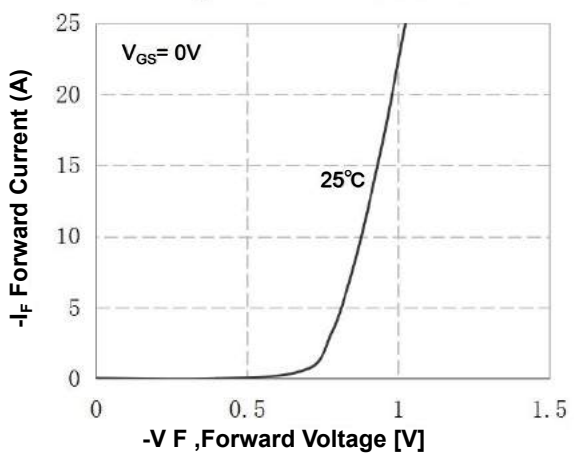


Figure 5. Body Diode Forward Voltage Variation with Source Current and Temperature

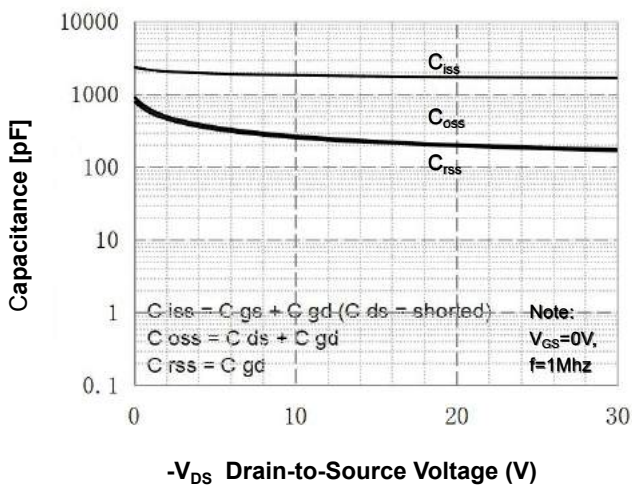


Figure 3. Capacitance Characteristics

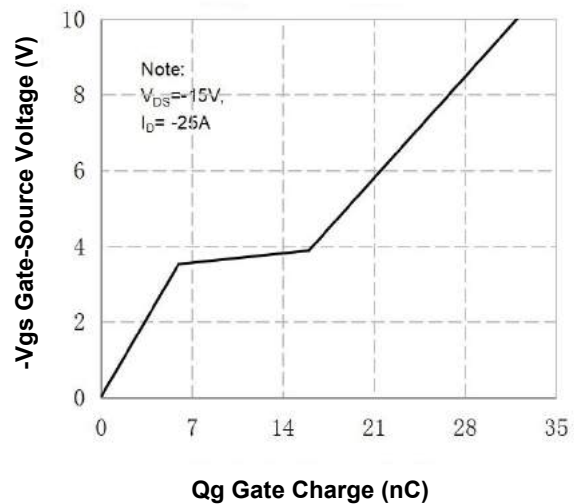


Figure 6. Gate Charge Characteristics

P- Channel Typical Characteristics (Continued)

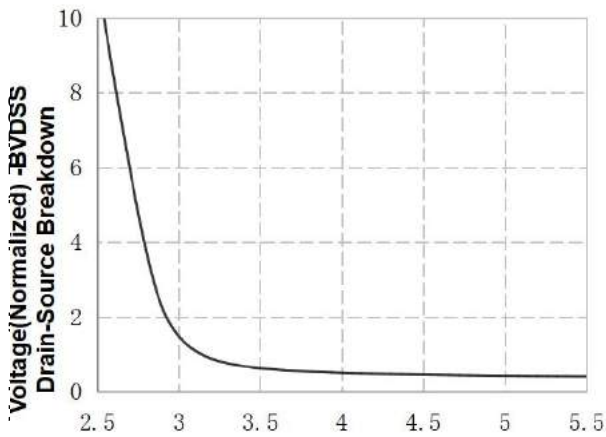


Figure 7. Breakdown Voltage Variation vs Gate-Voltage

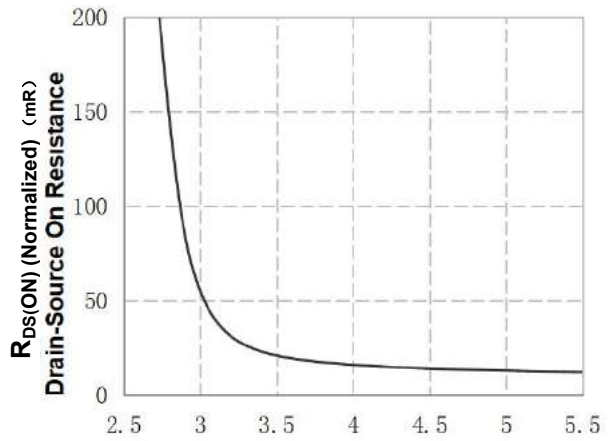


Figure 9. On-Resistance Variation vs Gate Voltage

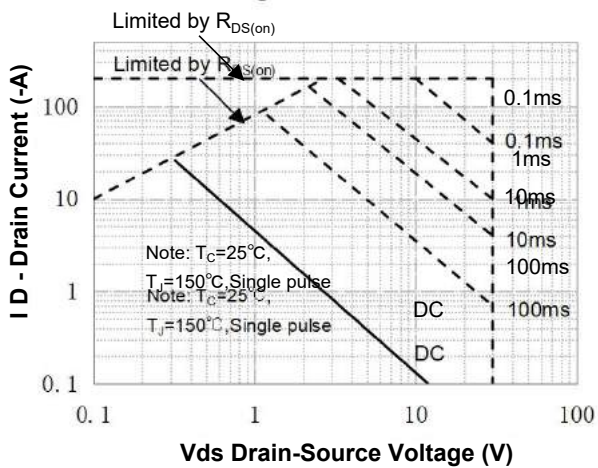


Figure 8. Maximum Safe Operating Area

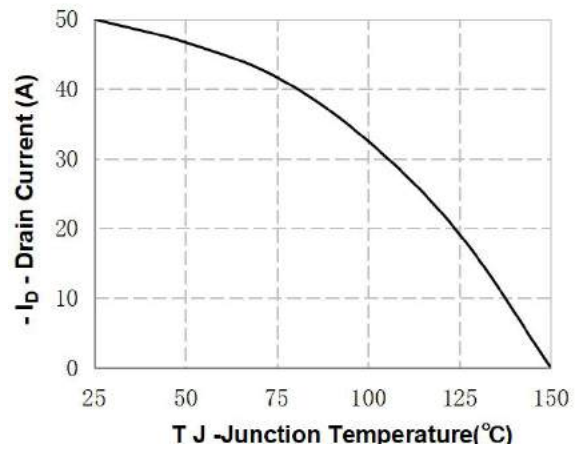


Figure 10. Maximum Continuous Drain Current vs Case Temperature

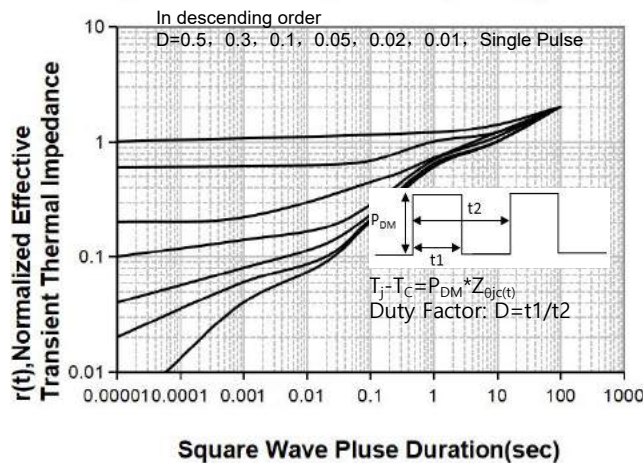
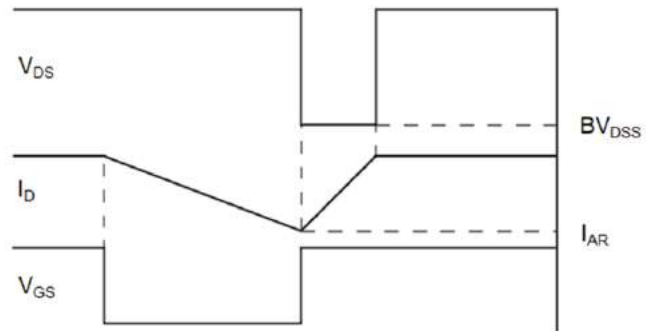
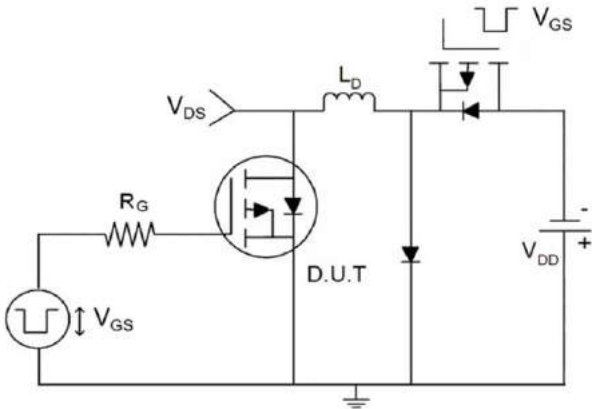


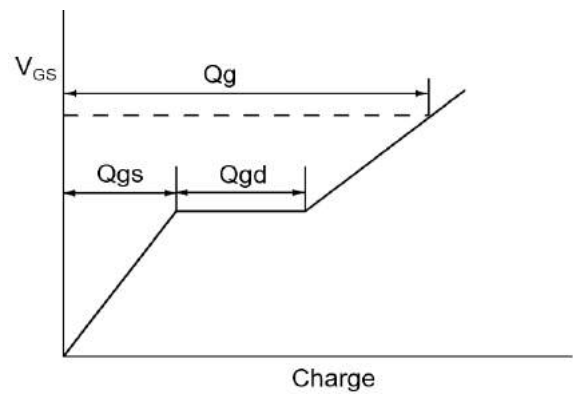
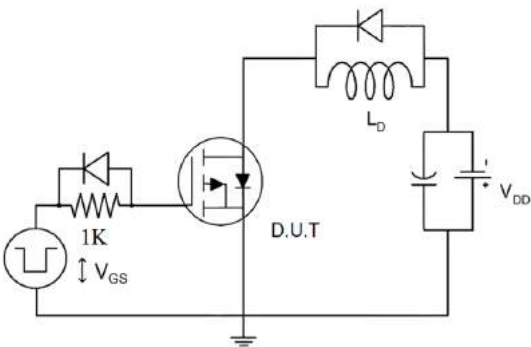
Figure 11 Transient Thermal Response Curve

Test Circuit

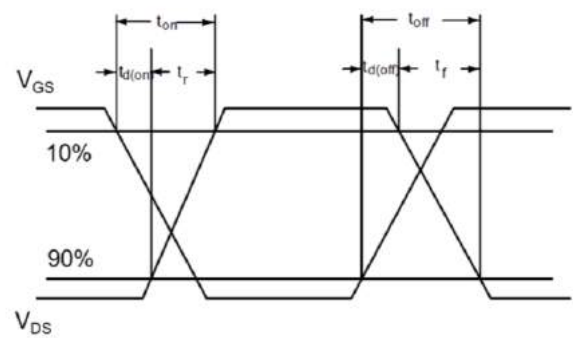
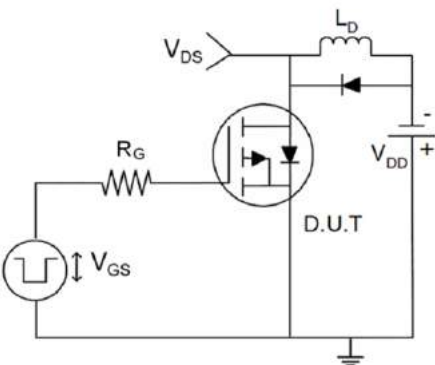
1) E_{AS} Test Circuits



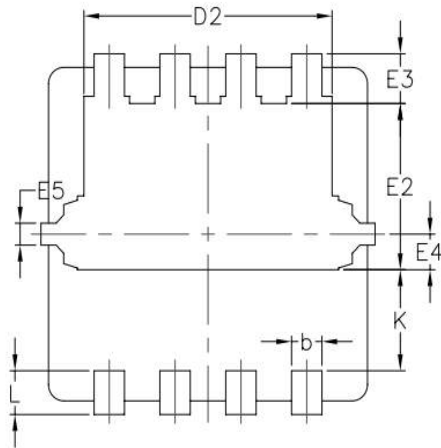
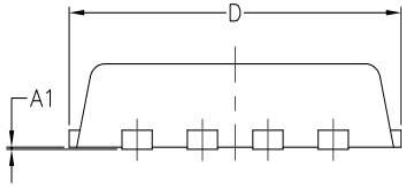
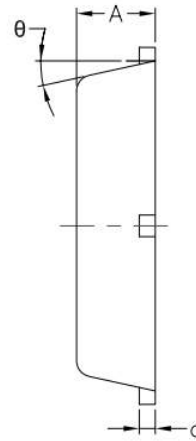
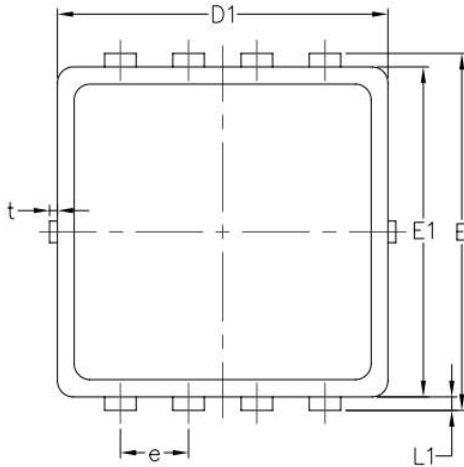
2) Gate Charge Test Circuit



3) Switch Time Test Circuit



DFN3x3-8L Package Information



SYMBOL	COMMON		
	MM		
	MIN	NOM	MAX
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.32	1.52	1.72
E3	0.28	0.46	0.65
E4	0.18	0.33	0.48
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.78	0.93	1.13
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
θ	10°	12°	14°

Customer Service

Sales and Service:

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